

Product Change Notification / KSRA-13AKNI696

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26-Feb-2021

Product Category:

8-bit Microcontrollers, Capacitive Touch Sensors, Touch Controllers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4440 Final Notice: Qualification of MMT as an additional assembly site for selected MTCH112, MTCH810 and PIC12xxxx device families available in 8L DFN (3x3x0.9mm) package.

Affected CPNs:

KSRA-13AKNI696_Affected_CPN_02262021.pdf KSRA-13AKNI696 Affected CPN 02262021.csv

Notification Text:

PCN Status: Final notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the icons found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of MMT as an additional assembly site for selected MTCH112, MTCH810 and PIC12xxxx device families available in 8L DFN (3x3x0.9mm) package.

Pre Change:

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, 8600 die attach material, EFTEC-64T lead frame or C194 lead frame material, Ag DAP surface prep or Bare Cu DAP surface prep and without lead lock lead frame

Post Change:

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, 8600 die attach

material, EFTEC-64T lead frame or C194 lead frame material, Ag DAP surface prep or Bare Cu DAP surface prep and without lead lock lead frame

or

Assembled at MMT using palladium coated copper wire with gold flash (CuPdAu) bond wire, 3280 die attach material, C194 lead frame material and Bare Cu DAP surface prep and with lead lock lead frame.

Pre and Post Change Summary:

	Pre C	hange	Post Change					
Assembly Site	UTAC Thai Lim	ited LTD. (NSEB)	UTAC Thai Lin (NSEB		Microchip Technology Thailand (Branch) / MMT			
Wire material	Au	CuPdAu	Au	CuPdAu	CuPdAu			
Die attach material	86	00	8600		3280			
Molding compound material	G70	OLTD	G700L	ΓD	G700LTD			
Lead frame material	EFTEC-64T	C194	EFTEC-64T	C194	C194			
Lead Frame DAP Surface Prep	Ag	Bare Cu	Ag	Bare Cu	Bare Cu			
Load from a load loak	N	0	No		Yes			
Lead frame lead-lock	See Pre and Post Change attachment for lead frame comparison							

Impacts to Data Sheet:None.

Change Impact:None.

Reason for Change:To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:

February 10, 2021 (date code: 2107)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2020			→	January 2021					February 2021					
Workweek	45	46	47	48	49		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date			Χ												
Final PCN Issue Date											Х				
Qual Report Availability															Χ
Estimated First Ship Date													Χ		

Method to Identify Change: Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:November 20, 2020: Issued initial notification. **January 29, 2021:** Issued final notification. Provided estimated first ship date to be February 10, 2021. **February 26, 2021:** Reissued final notification. Included qual report attachment and updated gual report availability.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_KSRA-13AKNI696_Pre_and_Post Change Summary.pdf PCN_KSRA-13AKNI696 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

PIC12F1822-E/MF

PIC12F1822-I/MF043

PIC12F1822-I/MF

PIC12F1822T-I/MF

PIC12F1822T-E/MF

PIC12LF1822-E/MF

PIC12LF1822-I/MF

PIC12LF1822T-I/MF

PIC12F1840-E/MF

MTCH810-I/MF

PIC12F1840-I/MF

PIC12F1840-H/MF

MTCH810T-I/MF

PIC12F1840T-I/MF

PIC12F1840T-E/MF

PIC12LF1840-E/MF

MTCH112-I/MF

PIC12LF1840-I/MF

MTCH112T-I/MF

PIC12LF1840T-I/MF

PIC12F1501-E/MF

PIC12F1501-I/MF

PIC12F1501T-E/MF

PIC12LF1501-E/MF

PIC12LF1501-I/MF

PIC12F1612-I/MF

PIC12LF1612-E/MF

PIC12F1571-E/MF

PIC12F1572-E/MF

PIC12F1571-I/MF059

PIC12F1571-I/MF

PIC12F1572-I/MF

PIC12F1571T-I/MF059

PIC12F1571T-I/MF

PIC12F1572T-I/MF

PIC12F1571T-E/MF

PIC12F1572T-E/MF

PIC12LF1571-E/MF

PIC12LF1572-E/MF PIC12LF1571-I/MF

PIC12LF1572-I/MF

PIC12LF1572T-I/MF

PIC12LF1572T-I/MFSIS

Date: Friday, February 26, 2021